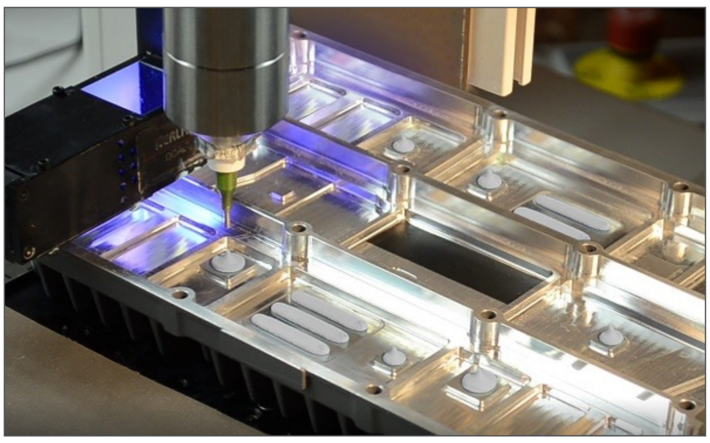
CHANNEL TALK

Laird™
A DuPont Business

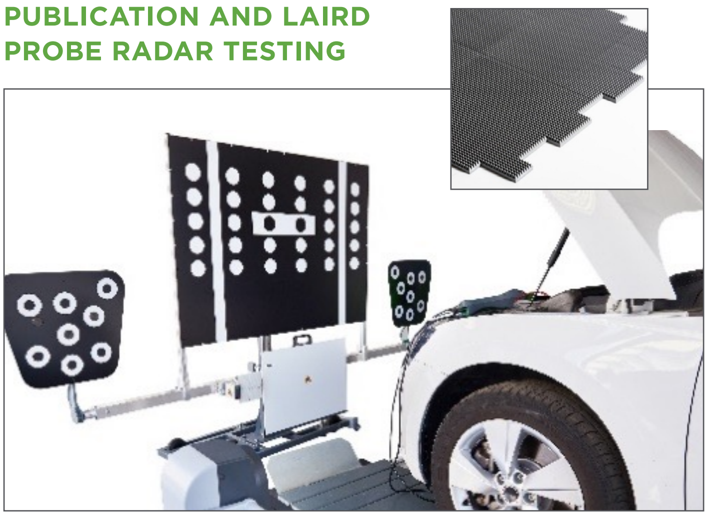
MAY 2024

TGEL™ 600 OFFERS BEST-IN-CLASS THERMAL RESISTANCE



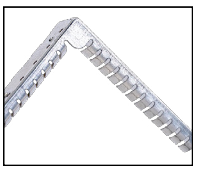
Now cooling the most demanding high wattage components, the new, versatile Laird™ Tgel™ 600 offers best-in-class thermal resistance in a variety of situations ranging from minimum bondline (~20µm) applications to large, fixed gap challenges up to 2mm. It is an all-in-one dispensable material solution meeting all thermal needs and ideal for effective, reliable heat transfer. With 6.4 W/mK bulk thermal conductivity, good vertical stability, and exhibiting minimal pump out, Tgel™ 600 can also be used within the same system package to serve as a gap filler and cool secondary components. It delivers low thermal resistance (<0.06°C-cm2/W). Tgel 600 is available in cans, pails, cartridges, and syringes and finds ideal applications in data centers, IGBTs, consumer electronics, telecom systems, and more. Review this exciting new entry in our thermal products line.

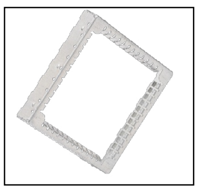
PUBLICATION AND LAIRD PROBE RADAR TESTING



While ADAS radar systems are designed to achieve maximum driver safety, inaccurate readings appearing during calibration and testing can contribute to dangerous maneuvering in traffic, driver misjudgments, and serious accidents. The importance of accurate ADAS radar testing has led to the growth of the radar calibration equipment market, projected to achieve an annual 11% growth rate, and hit USD 628 million in revenue by 2030. In "Testing to Ensure ADAS Radar Accuracy," a white paper appearing in May in *Automotive Testing Technology International,* we examine this topic end to end. False and unwanted radar reflections arising during ADAS calibration and testing can lead to inaccurate signal readings. An ideal testing solution for added accuracy is Laird™ Rezorb™ S absorber material. It delivers maximum absorber reflectivity performance in the mm wave frequency band and contrasts with the traditional use of absorber foam. Read this important white paper, encourage manufacturers to do likewise and visit our web page explaining Laird™ Rezorb™ S in greater detail.

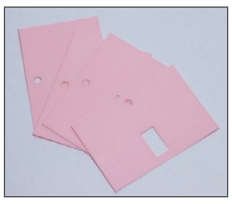
NEW SHIELD FRAME REQUIRES NO TOP COVER





BMI-S-608 is a new one-part EMI shielding solution from Laird with a range of current and potential applications within the automotive sector. More end markets are anticipated. Its four-sided shield frame is designed to remove complexity from the thermal transfer chain. It has no top-mount cover thus saving materials costs. Instead, the diecast/heat sink main housing (from a separate manufacturer) is placed directly inside the shield frame and is clasped tightly by integrated contact spring fingers. BMI-S-608 provides cost-effective EMI shielding of components while its spring fingers create electrical contact and grounding of the diecast/heat sink. The snug fit sealing of the diecast housing ensures it will retain direct, surface-to-surface contact with high thermal load integrated circuits. BMI-S-608 enhances design freedom involving PCB layouts, permits tighter spacing between adjacent shields, enables easier repairs of components, and serves as an alternative to multi-component manufacturer solutions. Learn more today.

NEW HIGH TEMP THERMALLY CONDUCTIVE ADHESIVE FILM



Eliminate cumbersome film attachment to surfaces using clips or screws with the new Laird™ brand Tgard™ TNC-6 Series, a heat curable self-adhesive film providing high electrical insulation and low thermal resistance. Its high temperature rating to 180°C and improved dielectric strength enable strong adhesion and lower contact resistance while enhancing superior thermal transfer. This high temperature thermally conductive adhesive is comprised of a single homogeneous thermally conductive silicone compound. By omitting fasteners, Tgard™ TNC-6 simplifies the application process as it adheres the power transistor to the heatsink with a low lamination pressure. Contact Laird to learn more about this effective and labor-saving solution for electronic device manufacturers.

DISCOVER THERMAL INTERFACE SOLUTIONS

THERMAL INTERFACE SOLUTIONS

Laird designs and manufactures customized, performance-critical products which enable and protect advanced electronics applications.

Help customers address and overcome complex heat transfer issues with Laird™ brand thermal interface materials. They can understand more benefits offered by Laird by using our comprehensive and newly updated digital booklet, ***Thermal Interface Solutions***. The booklet is a guide to the Laird line of industry-leading thermal interface materials, each engineered to resolve excessive thermal loads which are exacerbated by faster, higher power, and more densely packed components and systems. Included first are overviews and specifications of Laird thermal pads and liquid gap fillers. Our soft, thin, or ultra-thin thermal pads are complemented by Laird's line of stress minimizing, one- and two-part liquid gap fillers. Additional sections cover phase change materials, thermal greases, electrically isolating insulators, thermally conductive printed circuit boards, and graphite materials. Review our booklet today and see how customers can beat the heat.